

2872

APR 08 2002

TRANSMITTAL LETTER
(General - Patent Pending)

Docket No.
EN9-99-080

In Re Application Of: Caletka et al.

Serial No.
09/438,037

Filing Date
11/10/99

Examiner
Mitchell, J.

Group Art Unit
2827

Title: **PARTIALLY CAPTURED ORIENTED INTERCONNECTIONS FOR BGA PACKAGES
AND A METHOD OF FORMING THE INTERCONNECTIONS**

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is:

Amendment (9 pages)

in the above identified application.

- ☒ No additional fee is required.
- ☐ A check in the amount of _____ is attached.
- ☒ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. **09-0457 (IBM)** as described below. A duplicate copy of this sheet is enclosed.
- ☐ Charge the amount of _____
- ☐ Credit any overpayment.
- ☒ Charge any additional fee required.



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Dated: 4/2/2002

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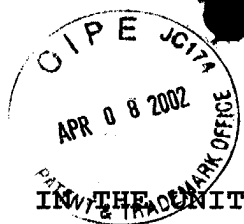
I certify that this document and fee is being deposited on 4/2/2002 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Signature of Person Mailing Correspondence

Lisa A. Molloy

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CC:



Docket No.: EN9-99-080

#9/a
4/12/02
Hawkins

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Caletka, et al.) Examiner: Mitchell, J.
Serial No.: 09/438,037) Art Unit: 2827
Filing Date: 11/10/99)
Title: PARTIALLY CAPTURED ORIENTED INTERCONNECTIONS FOR BGA
PACKAGES AND A METHOD OF FORMING THE INTERCONNECTIONS

Commissioner for Patents
Washington D.C. 20231

AMENDMENT

Sir:

In response to the Office Action mailed February 26, 2002,
please amend the above-identified patent application as follows:

IN THE CLAIMS:

Please amend the claims as follows:

14. (Amended) An integrated chip package comprising:

a first substrate and a second substrate, wherein the first
and second substrates include a plurality of partially captured
pads; and

a plurality of interconnections between the first and second
substrates.

Serial No.: 09/438,037

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